Features

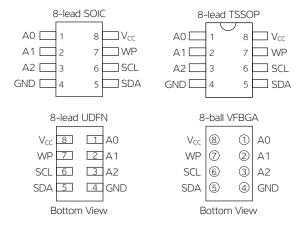
- · Low-voltage and standard-voltage operation
 - M for V_{CC} from 1.7V to 3.6V
 - D for V_{CC} from 2.5V to 5.5V
- Internally organized 65,536 x 8
- Two-wire serial interface
- Schmitt triggers, filtered inputs for noise suppression
- · Bidirectional data transfer protocol
- 1MHz (2.5V, 5.5V), 400kHz (1.7V) compatibility
- Write protect pin for hardware and software data protection
- 128-byte page write mode (partial page writes allowed)
- Self-timed write cycle (5ms max)
- High reliability
 - Endurance: 1,000,000 write cycles
 - Data retention: 40 years
- Lead-free/halogen-free devices
- 8-lead JEDEC SOIC, 8-lead EIAJ SOIC, 8-lead TSSOP, 8-lead UDFN, and 8-ball VFBGA packages
- Die sales: wafer form, waffle pack and bumped die

Description

The Atmel[®] AT24C512C provides 524,288 bits of serial, electrically erasable and programmable read-only memory (EEPROM) organized as 65,536 words of eight bits each. The device's cascadable feature allows up to eight devices to share a common two-wire bus. The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential. The devices are available in space-saving 8-lead JEDEC SOIC, 8-lead EIAJ SOIC, 8-lead TSSOP, 8-lead UDFN, and 8-ball VFBGA packages. The M voltage range devices operate from 1.7V to 3.6V. The D voltage range devices operate from 2.5V to 5.5V.

Figure 0-1. Pin Configurations

Pin Name	Function	
A0-A2	Address Inputs	
SDA	Serial Data	
SCL	Serial Clock Input	
WP	Write Protect	





Two-wire Serial, Electrically Erasable and Programmable Read-only Memory 512K (65,536 x 8)

Atmel AT24C512C with Three Device Address Inputs

8720A-SEEPR-9/10





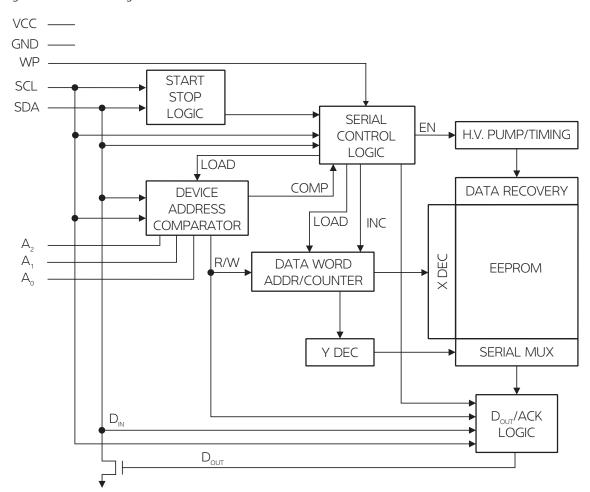
1. Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground1.0V to +7.0V
Maximum Operating Voltage6.25V
DC Output Current5.0mA

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 1-1. Block Diagram



2. Pin Description

SERIAL CLOCK (SCL): The SCL input is used to positive-edge clock data into each EEPROM device and negative-edge clock data out of each device.

SERIAL DATA (SDA): The SDA pin is bidirectional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open collector devices.

DEVICE/PAGE ADDRESSES (A2, A1, A0): The A2, A1, and A0 pins are device address inputs that are hardwired (directly to GND or to Vcc) for compatibility with other Atmel[®] AT24Cxx devices. When the pins are hardwired, as many as eight 512K devices may be addressed on a single bus system. (Device addressing is discussed in detail under "Device Addressing," page 8.) A device is selected when a corresponding hardware and software match is true. If these pins are left floating, the A2, A1, and A0 pins will be internally pulled down to GND. However, due to capacitive coupling that may appear during customer applications, Atmel recommends always connecting the address pins to a known state. When using a pull-up resistor, Atmel recommends using $10k\Omega$ or less.

WRITE PROTECT (WP): The write protect input, when connected to GND, allows normal write operations. When WP is connected directly to Vcc, all write operations to the memory are inhibited. If the pin is left floating, the WP pin will be internally pulled down to GND. However, due to capacitive coupling that may appear during customer applications, Atmel recommends always connecting the WP pins to a known state. When using a pull-up resistor, Atmel recommends using $10k\Omega$ or less.





3. Memory Organization

Atmel AT24C512C, 512K SERIAL EEPROM: The 512K is internally organized as 512 pages of 128 bytes each. Random word addressing requires a 16-bit data word address.

Table 3-1. Pin Capacitance⁽¹⁾

Symbol	Test Condition	Max	Units	Conditions
C _{I/O}	Input/Output Capacitance (SDA)	8	pF	$V_{I/O} = 0V$
C _{IN}	Input Capacitance (A ₀ , A ₁ , SCL)	6	pF	$V_{IN} = 0V$

Note: 1. This parameter is characterized and is not 100% tested

Table 3-2. DC Characteristics

Symbol	Parameter	Test Condition		Min	Тур	Max	Units
V _{CC1}	Supply Voltage					3.6	V
V _{CC2}	Supply Voltage			2.5		5.5	V
I _{CC}	Supply Current	V _{CC} = 5.0V	READ at 400kHz			2.0	mA
I _{CC}	Supply Current	V _{CC} = 5.0V	WRITE at 400kHz			3.0	mA
	Standby Current	$V_{CC} = 1.7V$., ., .,			1.0	μA
I _{SB1}		V _{CC} = 3.6V	$V_{IN} = V_{CC} \text{ or } V_{SS}$			3.0	μA
	Standby Current	$V_{CC} = 2.5V$	$V_{IN} = V_{CC}$ or V_{SS}			2.0	μA
I _{SB2}		V _{CC} = 5.5V				6.0	μA
ILI	Input Leakage Current	$V_{IN} = V_{CC} \text{ or } V_{SS}$	$V_{IN} = V_{CC} \text{ or } V_{SS}$		0.10	3.0	μA
I _{LO}	Output Leakage Current	$V_{IN} = V_{CC} \text{ or } V_{SS}$			0.05	3.0	μA
V _{IL}	Input Low Level ⁽¹⁾			-0.6		V _{CC} x 0.3	V
V _{IH}	Input High Level ⁽¹⁾			V _{CC} x 0.7		V _{CC} + 0.5	V
V _{OL1}	Output Low Level	$V_{CC} = 1.7V$	I _{OL} = 0.15mA			0.2	V
V _{OL2}	Output Low Level	V _{CC} = 3.0V	$I_{OL} = 2.1 \text{mA}$			0.4	V

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested

Table 3-3. AC Characteristics (Industrial Temperature)

			1.7V	2.5-5.0V		
Symbol	Parameter	Min	Max	Min	Max	Units
f _{SCL}	Clock Frequency, SCL		400		1000	kHz
t _{LOW}	Clock Pulse Width Low	1.3		0.4		μs
t _{HIGH}	Clock Pulse Width High	0.6		0.4		μs
t _i	Noise Suppression Time ⁽¹⁾		100		50	ns
t _{AA}	Clock Low to Data Out Valid	0.05	0.9	0.05	0.55	μs
t _{BUF}	Time the bus must be free before a new transmission can start ⁽¹⁾	1.3		0.5		μs
t _{HD.STA}	Start Hold Time	0.6		0.25		μs
t _{SU.STA}	Start Set-up Time	0.6		0.25		μs
t _{HD.DAT}	Data In Hold Time	0		0		μs
t _{SU.DAT}	Data In Set-up Time	100		100		ns
t _R	Inputs Rise Time ⁽¹⁾		0.3		0.3	μs
t _F	Inputs Fall Time ⁽¹⁾		300		100	ns
t _{SU.STO}	Stop Set-up Time	0.6		0.25		μs
t _{DH}	Data Out Hold Time	50		50		ns
t _{WR}	Write Cycle Time		5		5	ms
Endurance ⁽¹⁾	25°C, Page Mode, 3.3V	1,000,000			Write Cycles	

Notes: 1. This parameter is ensured by characterization only

2. AC measurement conditions:

R_L (connects to V_{CC}): 1.3kΩ (2.5V, 5V), 10 kΩ (1.7V) Input pulse voltages: 0.3V_{CC} to 0.7V_{CC} Input rise and fall times: ≤ 50ns Input and output timing reference voltages: 0.5V_{CC}





4. Device Operation

CLOCK and DATA TRANSITIONS: The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods (see Figure 4-4 on page 7). Data changes during SCL high periods will indicate a start or stop condition as defined below.

START CONDITION: A high-to-low transition of SDA with SCL high is a start condition which must precede any other command (see Figure 4–5 on page 7).

STOP CONDITION: A low-to-high transition of SDA with SCL high is a stop condition. After a read sequence, the stop command will place the EEPROM in a standby power mode (see Figure 4-5 on page 7).

ACKNOWLEDGE: All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a zero during the ninth clock cycle to acknowledge that it has received each word.

STANDBY MODE: The Atmel[®] AT24C512C features a low-power standby mode which is enabled: a) upon power up and b) after the receipt of the STOP bit and the completion of any internal operations.

SOFTWARE RESET: After an interruption in protocol, power loss or system reset, any two-wire part can be protocol reset by following these steps: (a) Create a start condition, (b) clock nine cycles, (c) create another start condition followed by a stop condition, as shown below. The device is ready for the next communication after the above steps have been completed.

Figure 4-1. Protocol Reset Condition

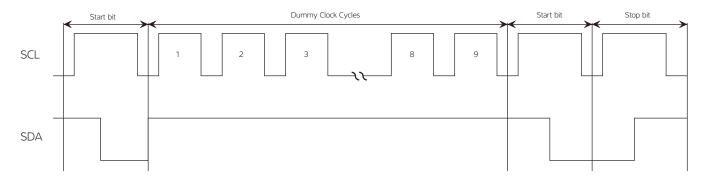


Figure 4-2. Bus Timing (SCL: Serial Clock, SDA: Serial Data I/O)

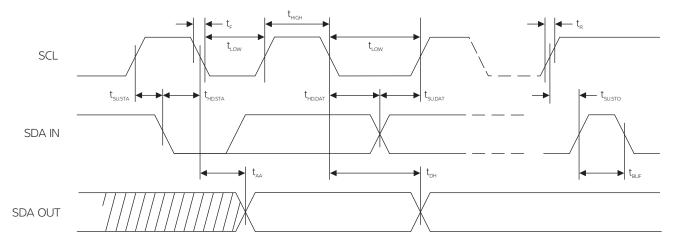
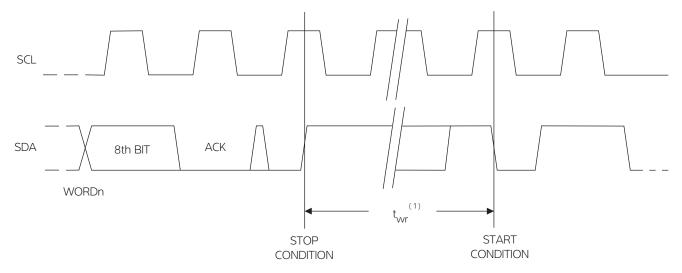
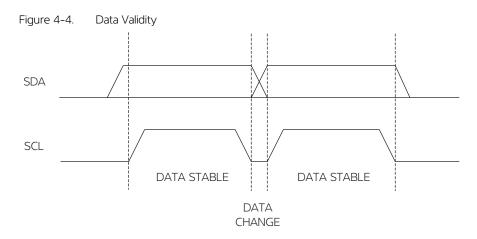


Figure 4-3. Write Cycle Timing (SCL: Serial Clock, SDA: Serial Data I/O)



Notes: 1. The write cycle time, t_{WR}, is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle



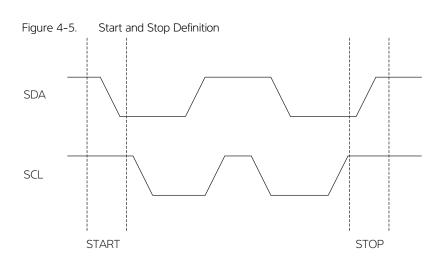
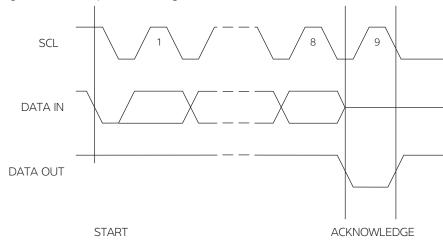






Figure 4-6. Output Acknowledge



5. Device Addressing

The 512K EEPROM requires an 8-bit device address word following a start condition to enable the chip for a read or write operation (see Figure 7-1 on page 9). The device address word consists of a mandatory one-zero sequence for the first four most-significant bits, as shown. This is common to all two-wire EEPROM devices.

The 512K uses the three device address bits A2, A1, and A0 to allow as many as eight devices on the same bus. These bits must compare to their corresponding hardwired input pins. The A2, A1, and A0 pins use an internal proprietary circuit that biases them to a logic low condition if the pins are allowed to float.

The eighth bit of the device address is the read/write operation select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

Upon a compare of the device address, the EEPROM will output a zero. If a compare is not made, the device will return to a standby state.

DATA SECURITY: The Atmel[®] AT24C512C has a hardware data protection scheme that allows the user to write protect the whole memory when the WP pin is at V_{CC} .

6. Write Operations

BYTE WRITE: A write operation requires two 8-bit data word addresses following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a zero and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a zero. The addressing device, such as a microcontroller, then must terminate the write sequence with a stop condition. At this time, the EEPROM enters an internally-timed write cycle, t_{WR}, to the nonvolatile memory. All inputs are disabled during this write cycle, and the EEPROM will not respond until the write is complete (see Figure 7-2 on page 10).

PAGE WRITE: The 512K EEPROM is capable of 128-byte page writes.

A page write is initiated the same way as a byte write, but the microcontroller does not send a stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to 127 more data words. The EEPROM will respond with a zero after each data word received. The microcontroller must terminate the page write sequence with a stop condition (see Figure 7-3 on page 10).

The data word address lower seven bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than 128 data words are transmitted to the EEPROM, the data word address will "roll over" and previous data will be overwritten. The address roll over during write is from the last byte of the current page to the first byte of the same page.

ACKNOWLEDGE POLLING: Once the internally-timed write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a start condition followed by the device address word. The Read/Write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a zero, allowing the read or write sequence to continue.

7. Read Operations

Read operations are initiated the same way as write operations with the exception that the Read/Write select bit in the device address word is set to one. There are three read operations: current address read, random address read, and sequential read.

CURRENT ADDRESS READ: The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address roll over during read is from the last byte of the last memory page to the first byte of the first page.

Once the device address with the Read/Write select bit set to one is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input zero, but does generate a following stop condition (see Figure 7-4 on page 10).

RANDOM READ: A random read requires a "dummy" byte write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a current address read by sending a device address with the Read/Write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a zero, but does generate a following stop condition (see Figure 7-5 on page 10).

SEQUENTIAL READ: Sequential reads are initiated by either a current address read or a random address read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address limit is reached, the data word address will roll over and the sequential read will continue. The sequential read operation is terminated when the microcontroller does not respond with a zero but does generate a following stop condition (see Figure 7-6 on page 10).

Figure 7-1. Device Address

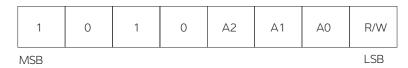






Figure 7-2. Byte Write

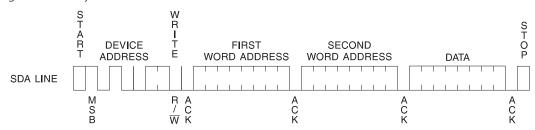


Figure 7-3. Page Write

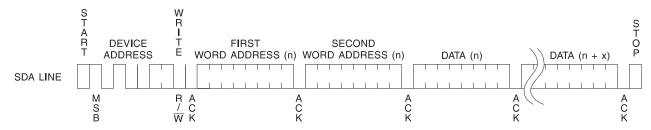


Figure 7-4. Current Address Read

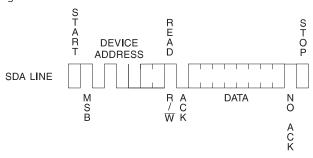


Figure 7-5. Random Read

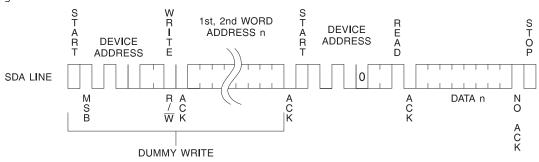
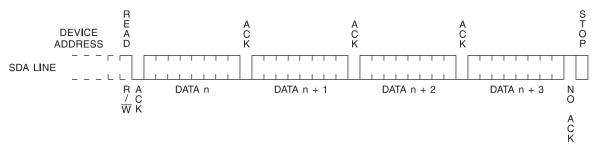
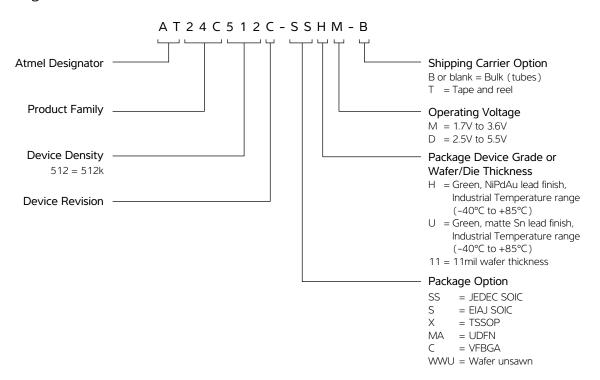


Figure 7-6. Sequential Read



8. Ordering Code Detail







9. Part Markings

Atmel AT24C512C-SSHM

Top Marking Only

```
|---|---|---|---|---|---|
A T M L H Y W W
|---|---|---|---|---|
2 F C M @
|---|---|---|---|---|
ATMEL LOT NUMBER
|---|---|---|---|---|
|
PIN 1 INDICATOR (DOT)
```

LINE 1: ATML=ATMEL H=MATERIAL SET/GRADE YWW=DATE CODE

LINE 2: 2FC=AT24C512C, M=1.7 to 3.6V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

No Bottom Marking

Atmel AT24C512C-SHM

Top Marking Only

```
|---|---|---|---|---|---|
A T M L H Y W W
|---|---|---|---|---|
2 F C M @
|---|---|---|---|---|
ATMEL LOT NUMBER
|---|---|---|---|
```

LINE 1: ATML=ATMEL H=MATERIAL SET/GRADE YWW=DATE CODE

LINE 2: 2FC=AT24C512C, M=1.7 to 3.6V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

Atmel AT24C512C-XHM

Top Marking Only

```
PIN 1 INDICATOR (DOT)

| |---|---|---|

* A T H Y W W

|---|---|---|---|

2 F C M @

|---|---|---|---|

ATMEL LOT NUMBER

|---|---|---|
```

LINE 1: AT=ATMEL, H=MATERIAL SET/GRADE, YWW=DATE CODE

LINE 2: 2FC=AT24C512C, M=1.7 to 3.6V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

No Bottom Marking

Atmel AT24C512C-MAHM

Top Marking Only

```
|---|---|
2 F C
|---|---|
H M @
|---|---|
Y X X
|---|---|
*
| PIN 1 INDICATOR (DOT)
```

LINE 1: 2FC=AT24C512C

LINE 2: H=MATERIAL SET/GRADE, M=1.7 to 3.6V, @=COUNTRY OF ASSEMBLY

LINE 3: Y=DATE CODE, XX=Trace Code

No Bottom Marking

Atmel AT24C512C-CUM

Top Marking Only

LINE 1: 2FC=AT24C512C, U=MATERIAL SET/GRADE

LINE 2: YM=DATE CODE, XX=Trace Code





Atmel AT24C512C-SSHD

Top Marking Only

```
|---|---|---|---|---|---|
A T M L H Y W W
|---|---|---|---|---|
2 F C D @
|---|---|---|---|---|
ATMEL LOT NUMBER
|---|---|---|---|---|
|
PIN 1 INDICATOR (DOT)
```

LINE 1: ATML=ATMEL H=MATERIAL SET/GRADE YWW=DATE CODE

LINE 2: 2FC=AT24C512C, D=2.5 to 5.5V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

No Bottom Marking

Atmel AT24C512C-SHD

Top Marking Only

LINE 1: ATML=ATMEL H=MATERIAL SET/GRADE YWW=DATE CODE

LINE 2: 2FC=AT24C512C, D=2.5 to 5.5V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

Atmel AT24C512C-XHD

Top Marking Only

```
PIN 1 INDICATOR (DOT)

| |---|---|---|

* A T H Y W W

|---|---|---|---|

2 F C D @

|---|---|---|---|
```

LINE 1: AT=ATMEL, H=MATERIAL SET/GRADE, YWW=DATE CODE

LINE 2: 2FC=AT24C512C, M=2.5 to 5.5V, @=COUNTRY OF ASSEMBLY

LINE 3: ATMEL LOT NUMBER

No Bottom Marking

Atmel AT24C512C-MAHD

Top Marking Only

```
|---|---|
2 F C
|---|---|
H D @
|---|---|
Y X X
|---|---|
PIN 1 INDICATOR (DOT)

LINE 1: 2FC=AT24C512C
LINE 2: H=MATERIAL SET/GRADE, D=2.5 to 5.5V, @=COUNTRY OF ASSEMBLY
LINE 3: Y=DATE CODE, XX=Trace Code
```

No Bottom Marking

Atmel AT24C512C-CUD

Top Marking Only

```
|---|---|---|
2 F C U
|---|---|---|
@ Y D X X
|---|---|---|
*
| PIN 1 INDICATOR (DOT)

LINE 1: 2FC=AT24C512C, U=MATERIAL SET/GRADE
LINE 2: YM=DATE CODE, XX=Trace Code
```





10. Ordering Codes

Atmel AT24C512C Ordering Information

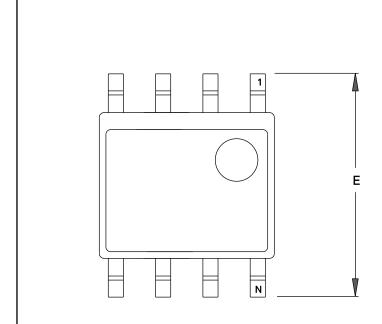
Ordering Code	Voltage	Package	Operation Range
AT24C512C-SSHM-B ⁽¹⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8S1	
AT24C512C-SSHM-T ⁽²⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8S1	
AT24C512C-SSHD-B ⁽¹⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8S1	
AT24C512C-SSHD-T ⁽²⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8S1	
AT24C512C-SHM-B ⁽¹⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8S2	
AT24C512C-SHM-T ⁽²⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8S2	
AT24C512C-SHD-B ⁽¹⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8S2	
AT24C512C-SHD-T ⁽²⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8S2	Lead-free/Halogen-free/ Industrial Temperature
AT24C512C-XHM-B ⁽¹⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8A2	(-40 to 85°C)
AT24C512C-XHM-T ⁽²⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8A2	(-40 to 83 C)
AT24C512C-XHD-B ⁽¹⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8A2	
AT24C512C-XHD-T ⁽²⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8A2	
AT24C512C-MAHM-T ⁽²⁾ (NiPdAu Lead Finish)	1.7V to 3.6V	8Y6	
AT24C512C-MAHD-T ⁽²⁾ (NiPdAu Lead Finish)	2.5V to 5.5V	8Y6	
AT24C512C-CUM-T ⁽²⁾ (matte Sn)	1.7V to 3.6V	8U2	
AT24C512C-CUD-T ⁽²⁾ (matte Sn)	2.5V to 5.5V	8U2	
AT24C512C-WWU11M ⁽³⁾	1.7V to 3.6V	Die Sale	Industrial Temperature
AT24C512C-WWU11D ⁽³⁾	2.5V to 5.5V	DIE Sale	(-40 to 85°C)

- Note: 1. "-B" denotes bulk delivery
 - 2. "-T" denotes tape and reel delivery. SOIC = 4K/reel, TSSOP, UDFN, and VFBGA = 5K/reel
 - 3. For wafer sales, please contact Atmel Sales

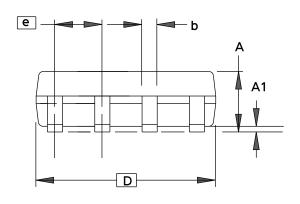
	Package Type				
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC)				
8S2	8-lead, 0.208" Wide, Plastic Gull Wing Small Outline Package (EIAJ SOIC)				
8A2	8-lead, 4.4mm Body, Plastic, Thin Shrink Small Outline Package (TSSOP)				
8Y6	8-lead, 2.00mm x 3.00mm Body, 0.50mm Pitch, Ultra Thin Dual No Lead Package (UDFN)				
8U2	8-ball, 2.35 x 3.73mm Body, 0.75mm Pitch, Small Die Ball Grid Array (VFBGA)				

11. Package Information

8S1 - JEDEC SOIC



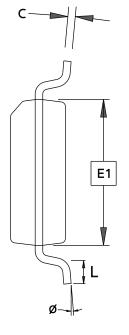
TOP VIEW



SIDE VIEW

Notes: This drawing is for general information only.

Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.



END VIEW

COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	1.35	-	1.75	
A1	0.10	-	0.25	
b	0.31	-	0.51	
С	0.17	-	0.25	
D	4.80	-	5.05	
E1	3.81	-	3.99	
Е	5.79	-	6.20	
е		1.27 BSC		
L	0.40	_	1.27	
Ø	O°	_	8°	

5/19/10



Package Drawing Contact: packagedrawings@atmel.com

TITLE 8S1, 8-lead (0.150" Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)

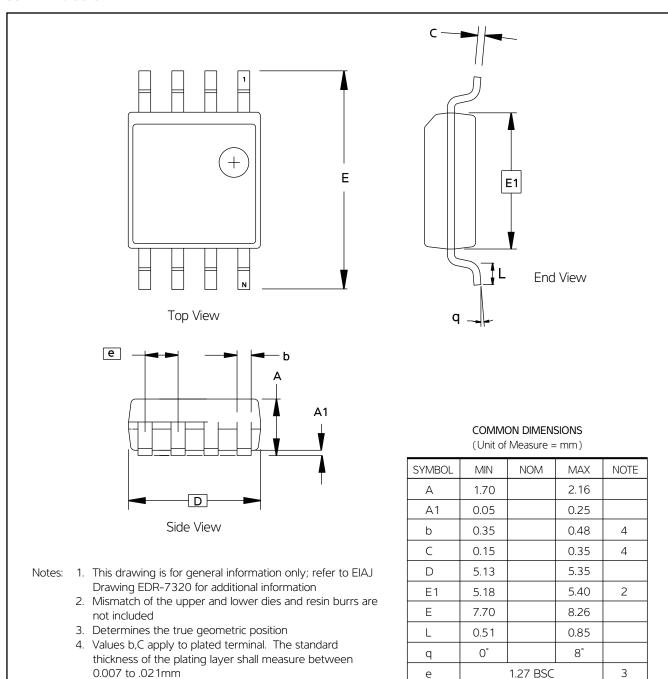
GPC	DRAWING NO.
SWB	8S1

REV.





8S2 - EIAJ SOIC

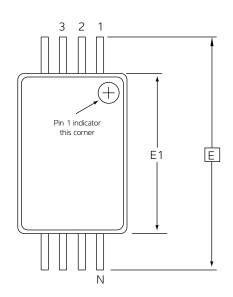


4/15/08

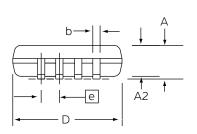




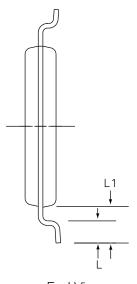
8A2 - TSSOP



Top View



Side View



End View

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
D	2.90	3.00	3.10	2, 5
Е	6.40 BSC			
E1	4.30	4.40	4.50	3, 5
А	-	-	1.20	
A2	0.80	1.00	1.05	
b	0.19	-	0.30	4
е				
L	0.45	0.60	0.75	
L1	1.00 REF			

Notes:

- 1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
- 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
- 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
- 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
- 5. Dimension D and E1 to be determined at Datum Plane H.

5/19/10 REV.

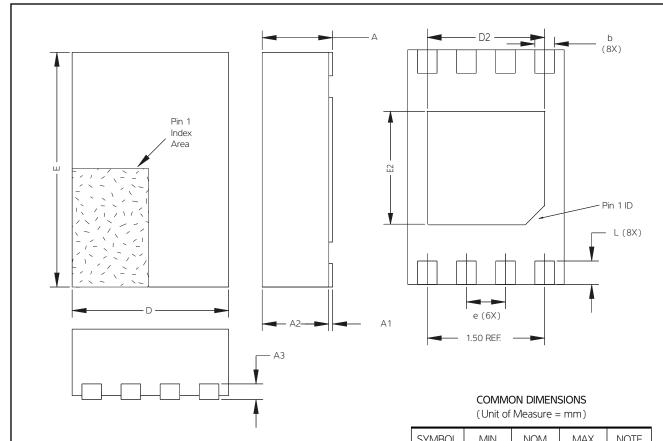


Package Drawing Contact: packagedrawings@atmel.com

8A2, 8-lead 4.4mm Body, Plastic Thin Shrink Small Outline Package (TSSOP) GPC DRAWING NO.
TNR 8A2

Е

8Y6 - UDFN



- Notes: 1. This drawing is for general information only. Refer to JEDEC Drawing MO-229, for proper dimensions, tolerances, datums, etc.
 - 2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension should not be measured in that radius area.
 - 3. Soldering the large thermal pad is optional, but not recommended. No electrical connection is accomplished to the device through this pad, so if soldered it should be tied to ground

SYIVIBUL	IVIIIV	NOM	IVIAX	NOTE		
D		2.00 BSC				
Е		3.00 BSC				
D2	1.40	1.50	1.60			
E2	_	-	1.40			
А	_	_	0.60			
Α1	0.00	0.02	0.05			
A2	_	_	0.55			
АЗ						
L	0.20	0.30	0.40			

0.50 BSC

0.25

11/21/08 REV.

Ε

2

Package Drawing Contact: packagedrawings@atmel.com TITLE 8Y6, 8-lead, 2.0x3.0mm Body, 0.50mm Pitch, UltraThin Mini-MAP, Dual No Lead Package (Sawn) (UDFN)

GPC YNZ

0.20

b

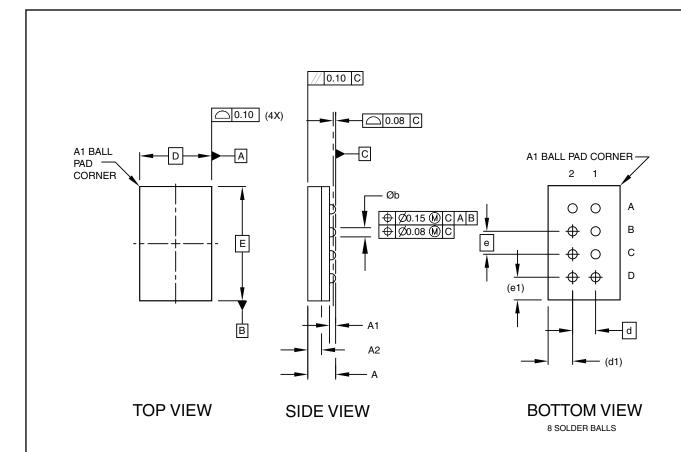
DRAWING NO. 8Y6

0.30





8U2-1 - dBGA2



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE		
Α	0.81	0.91	1.00			
A1	0.15	0.20	0.25			
A2	0.40	0.45	0.50			
b	0.25	0.30	0.35			
D	2	2.35 BSC				
Е		3.73 BSC				
е	(
e1	(
d	(0.75 BSC				
d1	(0.80 RE	EF			

07/23/10

57725110				
	TITLE	GPC	DRAWING NO.	REV.
	8U2-1, 8-ball, 2.35 x 3.73 mm Body, 0.75 mm pitch, VFBGA Package (dBGA2)	GWW	8U2-1	E

Notes:

1. This drawing is for general

2. Dimension 'b' is measured at the maximum solder ball diameter.

3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

12. Revision History

Doc. Rev.	Date	Comments
8720A	9/2010	Initial document release





Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131 USA

Tel: (+1) (408) 441-0311 **Fax:** (+1) (408) 487-2600

www.atmel.com

Atmel Asia Limited

Unit 01-5 & 16, 19F BEA Tower, Millennium City 5 418 Kwun Tong Road Kwun Tong, Kowloon HONG KONG

Tel: (+852) 2245-6100 **Fax:** (+852) 2722-1369

Atmel Munich GmbH

Business Campus Parkring 4 D-85748 Garching b. Munich GERMANY

Tel: (+49) 89-31970-0 **Fax:** (+49) 89-3194621

Atmel Japan

9F, Tonetsu Shinkawa Bldg. 1–24-8 Shinkawa Chuo-ku, Tokyo 104-0033 JAPAN

Tel: (+81) (3) 3523-3551 **Fax:** (+81) (3) 3523-7581

© 2010 Atmel Corporation. All rights reserved. / Rev.: 8720A-SEEPR-9/10

Atmel[®], logo and combinations thereof, Everywhere You Are[®] and others are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.

Distainer: The information in this document is provided in connection with Almel products. Noticense, express or implied, by estapped or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Almel products. EXCEPT AS SET FORTH NITHE ATMEL TERMS AND CONDITIONS OF SALES LOCATED ON THE ATMEL ASSUMES NO LUBBLITY VWHATSOENERAND DOSCLAMS, ANY EXPRESS, MPLED OR STATUTIONY VWHATANITY RELATING TO ITS PRODUCTS INCLUDING, BUTNOT LUMIDED TO, THE MPLED WARRANITY OF MERCHANITABLITY, RINESS FOR A PARTICULAR PURPOSE, OR NON-NAPPINDEWINST, IN NO EVENT SHALL ATMEL BE LURBLE FOR ANY DIRECT, CONSEQUENTIAL, PLANITIVE SPECIAL OR INCOBINITAL DAWAGES (INCLUDING, WITHOUT LUTITATION), DAWAGES FOR LOSS AND PROFITS, BUSINESS NITERRUPTION, OR LOSS OF INFORMATION).
A PRISING OUT OF THE USE OR INVABILITY TO USE THIS DOCUMENT, EVENT ATMEL HAS BEEN ADVISED OF THE POSSBUTTY OF SUCH DAWAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and products descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein Unless specifically provided otherwise. Atmel products are not suitable for, and shall not be used in automotive applications. Atmel products are not suitable for, and shall not be used in automotive applications. Atmel products are not suitable for, and shall not be used in automotive applications. Atmel products are not suitable for, and shall not be used in automotive applications at media automotive applications intended to support or sustain life.